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REVISIONS

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.26	阿树

A

A

B

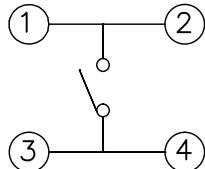
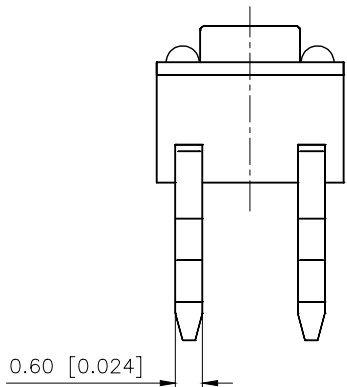
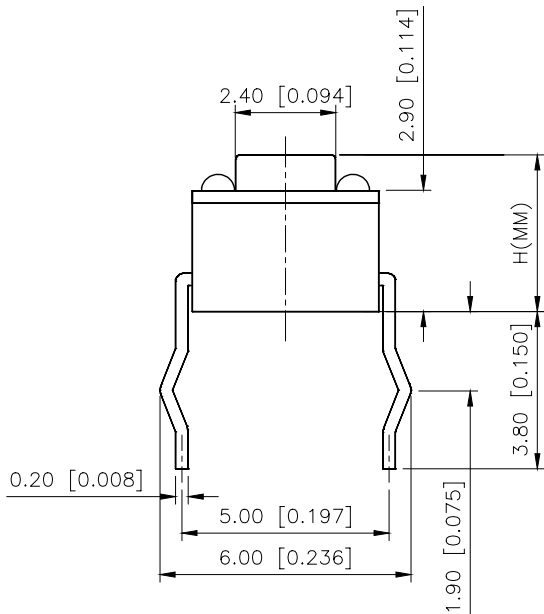
B

C

C

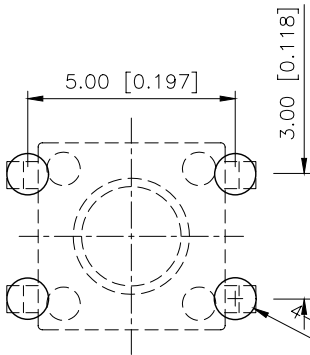
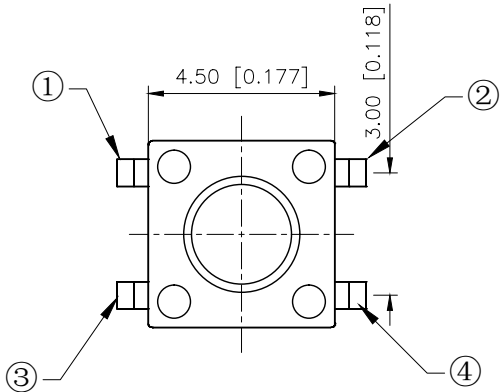
D

D



CIRCUIT DIAGRAM

Code-x	H
A	3.80
B	4.30
C	4.50
D	5.00
E	5.50
F	6.00
G	6.50
H	7.00
I	7.50
J	8.00
K	8.50
L	9.00



P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are
recommended for reflow soldering

SPECIFICATION

Contact Rating: 50mA,12V DC
Contact Resistance: 100mΩ max
Insulation Resistance: 100MΩ min.500V DC
Dielectric Strength: 250V AC/1minute
Travel: 0.25mm
Operating Temp: -30℃~+85℃
Storage Temp: -30℃~+80℃

PAPT NO	TC-1109-B-J
Operating Force	A:100gf B:160gf C:260gf
Height	Code-x

⑤	Terminal	4	Brass (0.30t)	Plating silvering
④	Contact	1	F.ag/SUS	Natural
③	Base	1	PA46	
②	Cover	1	Spcc	Plating Nickel
①	Keystake	1	PA46	
ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN

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VIEW:



MODEL TYPE:

TACT SWITCH

CHECKED

UNIT:

mm/in

PART NO.:

TC-1109-B-J

APPROVED

SIZE:

A4

DWG NO.:

TC-1109-B-J

SCALE

PAGE

REVISION

N/A

1/1

A1

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